

DYO LED ELECTRONICS LIMITED

Room 1610, Hong Kong Plaza, 188 Connaught Road West, Hong Kong.Tel : (852) 2540 7288Fax : (852) 2517 1797http://www.toyo-led.comE-mail : sales@toyo-led.com



P/N: TY-5050RGB3

5.0 * 5.0mm TOP SMD Series

SPECIFICATION FOR CUSTOMER APPROVAL

P/N:TY-5050RGB3

DATE	•	August 18, 2015
DIML	•	Tugust 10, 2015

PREPARED BY : Chen Lifen

CONFIRMED BY : Yan Guoliang

PLEASE CONFIRM & SIGN BACK THIS SHEET TO US

CUSTOMER:

APPROVAL BY:

(COMPANY CHOP)

(SIGNATURE)

TOYO LED ELECTRONICS LIMI TED

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P/N: TY-5050RGB3

♦ **Features:**

- 5.0mm×5.0mm SMT LED, 1.60mm thickness \geq
- PLCC-6 package \geq
- \triangleright White package
- Suitable for all SMT assembly and solder process \triangleright
- ≻ Available on 8mm tape and on 178mm reel

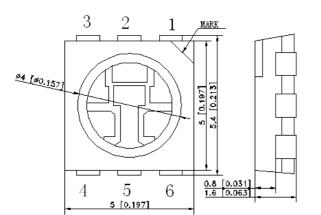
Description ∻

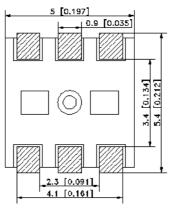
The Yellow source color devices are made with AlGaInP on sapphire Light Emitting Diode.

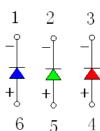
♦ Application

- ⊳ Optical indicator
- \triangleright Indicator and backlighting in telephone and fax
- Flat backlight for LCD, switch and symbol \triangleright
- Light pipe application \triangleright
- General use

Package Outline Dimensions ∻







NOTES :

- 1. All dimensions are in millimeter;
- 2. Tolerance is±0.2mm unless other specified;
- 3. Specifications are subject to change without notice.





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Max

Unit

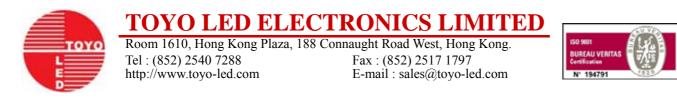
Part No.	Emitted Color		Len	Len's Color		Chip Material		
TY-5050RGB3	Red Green	Blue	Water clear		InGaN	InGaN	InGaN	
Absolute Maximum Ratings(7	Га=25)							
Iter	m		Syn	nbol	Maximum	U	nit	
				R	60			
Power Dissipation		Pd	G	95	m	W		
			В	110				
Forward Current		In	R/B	30				
		IF	G	25	m	mA		
Peak Forward Current(1/10 Duty Cycle 0.1ms Pulse			Ifp	R/G	150	mA		
Width)				В	160			
Reverse Voltage		V	′R	5	V			
Operating Temperature Range		Top	/ Tstg	-40 to+85				
Operating Temperature Range			Y					

1	(,		
Item	Syn	nbol	Condition	Min.	Тур.
Forward Voltago	VF	R	IF=20mA	1.8	2.2
Forward Voltage	VF	G/B	IF-20IIIA	2.8	3.2
		R		400	700

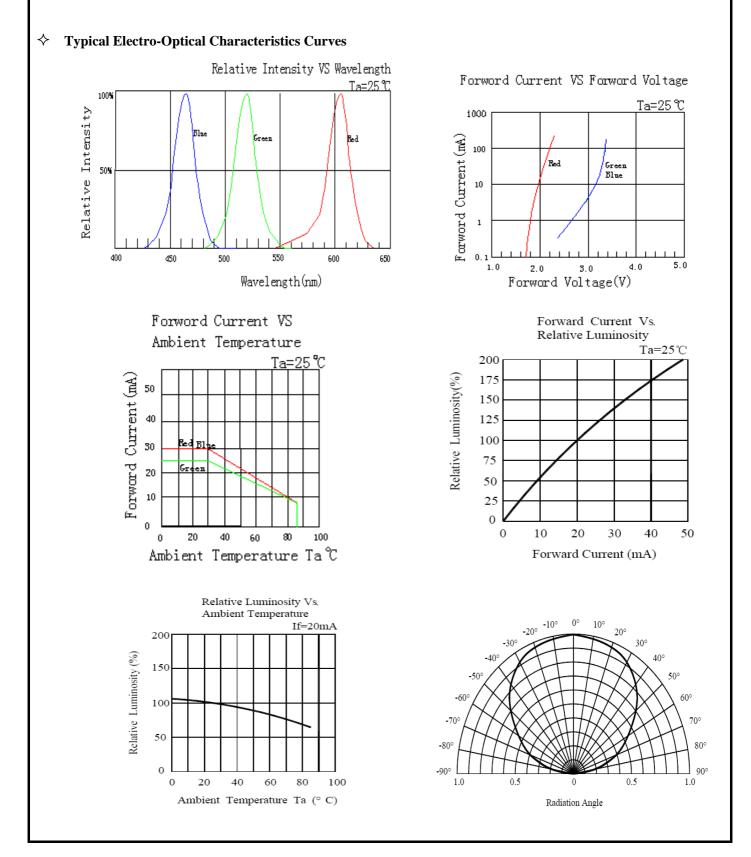
Forward Voltage	VF	R	IF=20mA	1.8	2.2		V
Forward Voltage	VF	G/B	IF-20IIIA	2.8	3.2		v
		R		400	700		
Luminous Intensity	Iv	G	IF=20mA	900	1200		mcd
		В		200	400		
		R		620	622	625	
Wavelength	λ	G	IF=20mA	520	522	525	nm
		В		460	465	470	
Viewing Angle	26	1/2	IF=20mA		120		deg
Reverse Current		R	$V_R = 5V$		5	10	uA

NOTES:

- Tolerance is ± 0.25 mm unless other specified; 1.
- 2. Luminous intensity testing tolerance is $\pm 10\%$;
- Dominant Emission Wavelength testing tolerance is $\pm 5\%$; 3.
- 4 Specifications are subject to change without notice.



5.0 * 5.0mm TOP SMD Series



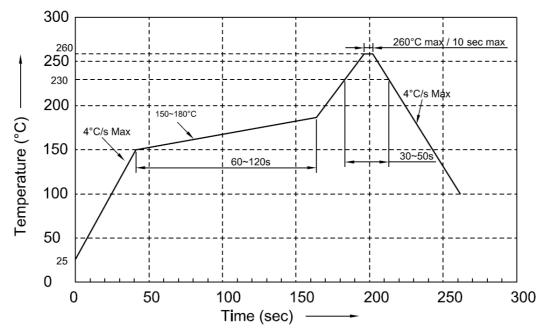




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Reliability T	eliability Test Items And Conditions							
NO.	Item	Test Condition	Test Hr/cycle/time	Sample Qty	Ac/Re			
1	Reflow	TEMP:260±5 ; (3-7 sec)	6 min	22pcs	0/1			
2	High Temperature /Humidity Storage	TEMP: 85 / R.H.:85%	1000hrs	22pcs	0/1			
3	Low Temperature Storage	TEMP: -40	1000hrs	22pcs	0/1			
4	DC Operating Life	IF=20mA	1000hrs	22pcs	0/1			

♦ Recommended SMT Reflow Soldering Instructions



Notes:

- 1. We recommend the reflow temperature 245±5 .The maximum soldering temperature should be limited to 260 for 10s (max).
- 2. Don't cause stress to the epoxy resin while it is exposed to high temperature.
- 3. Number of reflow process shall be 2 times or less.

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♦ Handling Precautions

Epoxy resin is hard & brittle and silicone is softer & flexible. Although its characteristic significantly thermal stress, it is more susceptible to damage by external mechanical force.

As a result, special handling precautions need to be observed during assembly using silicone encapsulated

- LED products. Failure to comply might lead to damage and premature failure of the LED.
- 1. Handle the component along the side surface by using forceps or appropriate tools (fig.1); do not directly touch or Handle the silicone lens surface, it may damage the internal circuitry(fig.2&3).



- 2. The outer diameter of the SMD pickup nozzle should not exceed the size of the LED to prevent air leaks. The inner diameter of the nozzle should be as large as possible. A pliable material is suggested for the nozzle tip to avoid scratching or damaging the LED surface during pickup. The dimensions of the component must be accurately programmed in the pick-and-place machine to insure precise pickup and avoid damage during production.
- 3. Prevent stack together assembled PCBs containing. PH<7. LEDs. Impact may scratch the silicone lens or damage the internal circuitry(fig.4).





4. Non-suitable to operate in acidic environment,

5. LED operating environment and sulfur element composition cannot be over 100PPM in the LED mating usage material.

(Fig.5)

♦ ESD (Electrostatic Discharge)

Static Electricity or power surge will damage the LED. Use of a conductive wrist band or anti-electrostatic glove is recommended when handing these LED. All devices, equipment and machinery must be properly grounded.

♦ Storage

In order to prevent the absorption of moisture, it is recommended to solder TOYO LEDs as soon as possible after unpacking the sealed envelope.

If the envelope is still packed, to store it in the environment as following:

Temperature:5 -30 (41 -86) Humidity: RH 60% Max.

After this bag is opened, devices that will be applied to infrared reflow, vapor-phase reflow, or equivalent soldering process must be:

- A, Completed within 168 hours.
- B、 Stored at less than 30% RH.

Devices required baking before mounting, if:(2)a or (2)b is not met.

If baking is required, devices must be baked under below condition:48 hour at 60 ± 3 .



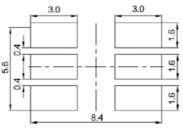


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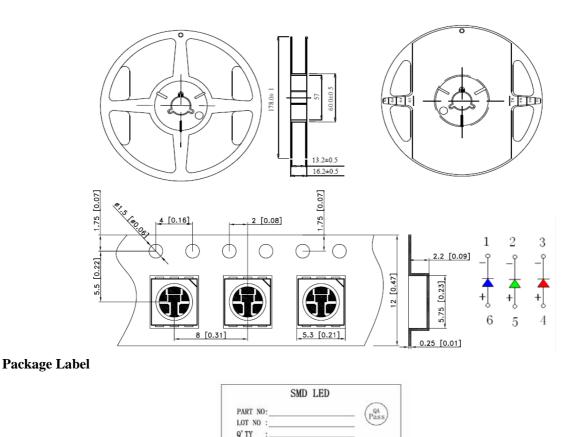
♦ Other

- 1. Above specification may be changed without notice. TOYO will reserve authority on material change for above specification.
- 2. When using this product, please abserve the absolute maximum ratings and the instructions for using outlined in these specification sheets. TOYO assumes no responsibility for any damage resulting from use of the product which does not comply with the absolute maximum ratings and the instructions included in these specification sheets.
- 3. These specification sheets include materials protected under copyright of TOYO LED ELECTRONICS LIMITED. Please don't reproduce cause by anyone to reproduce them without TOYO's consent.

♦ Recommended Soldering Pad Dimensions



♦ Tape Specification: 2,000pcs per reel



IV :

BIN:

TOYO LED ELECTRONICS LIMITED

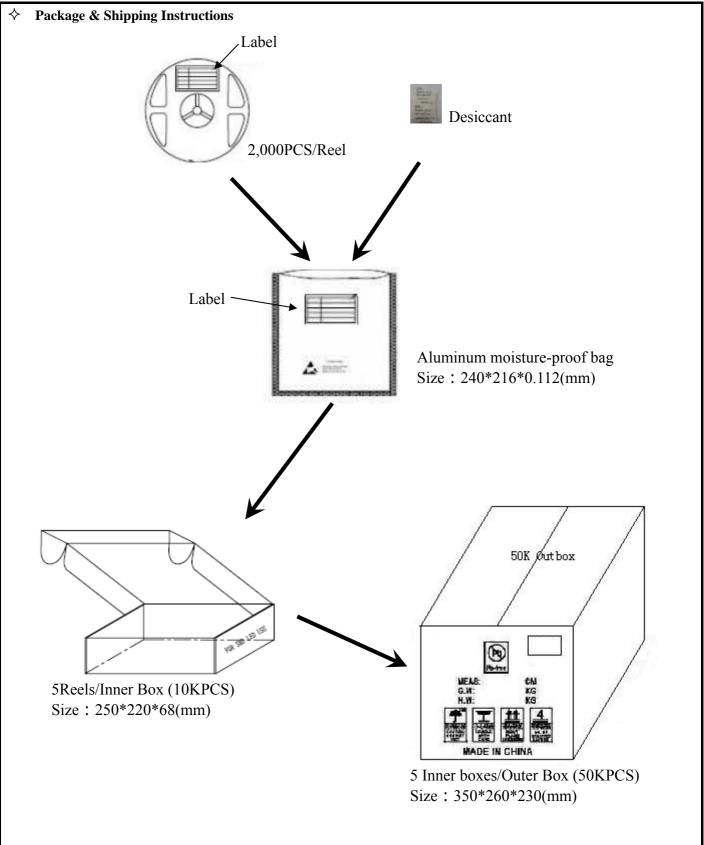
VF :

WL :

DATA











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DATE	REVISION CONTENTS	VERSION
2015-08-18	New	А

REVISION HISTORY